#### PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE:      | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT     |

#### **CONVEYING PARTY DATA**

| Name            | Execution Date |
|-----------------|----------------|
| KAMAL K SIKKA   | 06/25/2011     |
| HILTON T TOY    | 06/21/2011     |
| KRISHNA R TUNGA | 06/21/2011     |
| JEFFREY A ZITZ  | 06/21/2011     |

#### **RECEIVING PARTY DATA**

| Name:           | International Business Machines Corporation |
|-----------------|---|
| Street Address: | New Orchard Road                            |
| City:           | Armonk                                      |
| State/Country:  | NEW YORK                                    |
| Postal Code:    | 10504                                       |

#### PROPERTY NUMBERS Total: 1

| Property Type       | Number   |
|---------------------|----------|
| Application Number: | 13169394 |

#### **CORRESPONDENCE DATA**

Fax Number: (845)892-6363

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 8458943363

Email: nesheh@us.ibm.com
Correspondent Name: Joseph Petrokaitis
Address Line 1: 2070 Route 52

Address Line 2: 482

Address Line 4: Hopewell Junction, NEW YORK 12533

| ATTORNEY DOCKET NUMBER: | FIS920110087US1    |
|-------------------------|--------------------|
| NAME OF SUBMITTER:      | Joseph Petrokaitis |

PATENT REEL: 026640 FRAME: 0747

501604523

Total Attachments: 8



PATENT REEL: 026640 FRAME: 0748

#### **ASSIGNMENT**

Whereas, the undersigned Inventor(s) has/have made certain inventions, improvements, and discoveries (herein referred to as the "Invention") in:

Title of the Invention:

## MULTICHIP ELECTRONIC PACKAGES AND METHODS OF MANUFACTURE

| and further identified by the IBM Docket Number provided above in the header of this Assignment, for which an application for a United States Patent was executed concurrently herewith or was filed having: |   |  |
|--|---|--|
| Serial Number:   | (insert series code and serial number here if/when available)   |  |
| business at Armonk, New Yor<br>Inventor desires to grant to IB   | ess Machines Corporation, a corporation of New York having a place of rk (herein referred to as "IBM"), desires to acquire, and each undersigned M, the entire worldwide right, title, and interest in and to the Invention and pplications and patents directed thereto; |  |

Now, therefore, for good and valuable consideration, the receipt and sufficiency thereof being hereby acknowledged, each undersigned Inventor ("ASSIGNOR") hereby sells, assigns, and otherwise transfers to IBM (the "ASSIGNEE"), its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the Invention, the above-identified United States patent application, and any and all other patent applications and patents for the Invention which may be applied for or granted therefor in the United States and in all foreign countries and jurisdictions, including all divisions, continuations, reissues, reexaminations, renewals, extensions, counterparts, substitutes, and extensions thereof, and all rights of priority resulting from the filing of such applications and granting of such patents. In addition, each undersigned Inventor hereby authorizes and requests the Director of the United States Patent and Trademark Office to issue any United States Patent, and foreign patent authorities to issue any foreign patent, granted for the Invention, to IBM, its successors, legal representatives, and assigns, the entire worldwide right, title, and interest in and to the same to be held and enjoyed by IBM, its successors, legal representatives, and assigns to the full end of the terms for which any and all such patents may be granted, as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made; and each undersigned Inventor agrees to execute any and all documents and instruments and perform all lawful acts reasonably related to recording this Assignment or perfecting title to the Invention and all related patents and applications, in IBM, its successors, legal representatives, and assigns, whenever requested by IBM, its successors, legal representatives, or assigns.

Each undersigned Inventor acknowledges their prior and ongoing obligations to sell, assign, and transfer the rights under this Assignment to IBM and is unaware of any reason why they may not have the full and unencumbered right to sell, assign, and transfer the rights hereby sold, assigned, and transferred, and has not executed, and will not execute, any document or instrument in conflict herewith. Each undersigned Inventor also hereby grants IBM, its successors, legal representatives, and assigns, the right to insert in this Assignment any further identification (including, but not limited to, patent application Serial Number) which may be necessary or desirable for recordation of this Assignment. This Assignment is governed by the substantive laws of the State of New York, and any disputes will be resolved in a New York state court or federal court sited in New York.

[Inventor Signature Page(s) Follows]

Daga 1 of 7

|            | Executed by Inventor 1          |  |
|------------|---------------------------------|--|
| Signature: | Kamal K. SIKKA  Date: 6/25/2011 |  |
|            | Executed by Inventor 2          |  |
| Signature: | Hilton T. TOY                   |  |
| ·          | Executed by Inventor 3          |  |
| Signature: | Date: Krishna R. TUNGA          |  |
|            | Executed by Inventor 4          |  |
| Signature: | Jeffrey A. ZITZ                 |  |

Daga 7 of 7

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|  | ss Machines Corporation, a corporation of New York having a place of           |  |
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| Inventor desires to grant to IB!   | M, the entire worldwide right, title, and interest in and to the Invention and |  |
| in and to any and all patent app   | plications and patents directed thereto;                                       |  |

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[Inventor Signature Page(s) Follows]

| Executed by Inventor 1 |                            |  |
|------------------------|----------------------------|--|
| Signature:             | Date:                      |  |
|                        | Executed by Inventor 2     |  |
| Signature:             | Haf 7. 77 Date: 06/21/2011 |  |
|                        | Executed by Inventor 3     |  |
| Signature:             | Date: Krishna R. TUNGA     |  |
|                        | Executed by Inventor 4     |  |
| Signature:             | Date: Jeffrey A. ZITZ      |  |

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[Inventor Signature Page(s) Follows]

|                             | Executed by Inventor 1 |       |
|-----------------------------|------------------------|-------|
| Signature:Kamal K. SIKKA    | Date:                  |       |
|                             | Executed by Inventor 2 |       |
| Signature: Hilton T. TOY    | Date:                  |       |
| ,                           | Executed by Inventor 3 | *, *, |
| Signature: Krishna R. TUNGA | Date: June 21 7 2011   |       |
|                             | Executed by Inventor 4 |       |
|                             |                        |       |
| Signature:                  | Date:                  |       |

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[Inventor Signature Page(s) Follows]

Page 1 of 2

|            | Executed by Inventor 1          |
|------------|---------------------------------|
| Signature: | Mamai K. SIKKA                  |
|            | Executed by Inventor 2          |
| Signature: | Date:Date:                      |
|            | Executed by Inventor 3          |
| Signature: | Date: Date:                     |
|            | Executed by Inventor 4          |
| Signature: | Jestrey/A. ZIYZ Date: 6/21/2011 |

Page 2 of 2

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**PATENT** 

**RECORDED: 07/25/2011 REEL: 026640 FRAME: 0756**